

旺矽科技股份有限公司

6223.TT



Presentation Disclaimer

The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

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Probe Card

Since
1995

2

Photonics
Automation

Since
2001

3

Advanced
Semiconductor
Test

Since
2014

4

Thermal Test

Since
2015

5

Celadon
Systems

Since
2021



MPI 全球據點

MPI ATV SYSTEMS

MPI SUZHOU

MPI AMERICA

MPI CELADON

MPI FOCUS MICROWAVES

MPI CORPORATION

- MPI Operation Offices
- MPI Sales & Support Offices
- MPI Representatives

MPI Locations

Worldwide

Taiwan



MPI America
USA (2017)



MPI Suzhou
China (2017)



Celadon Systems
USA (2021)



ATV Systems
Germany (2025)



Focus Microwaves
Canada (2025)



Headquarters
TW (2000)



Luzhu Office
TW (2006)



2nd Production Site
TW (2012)

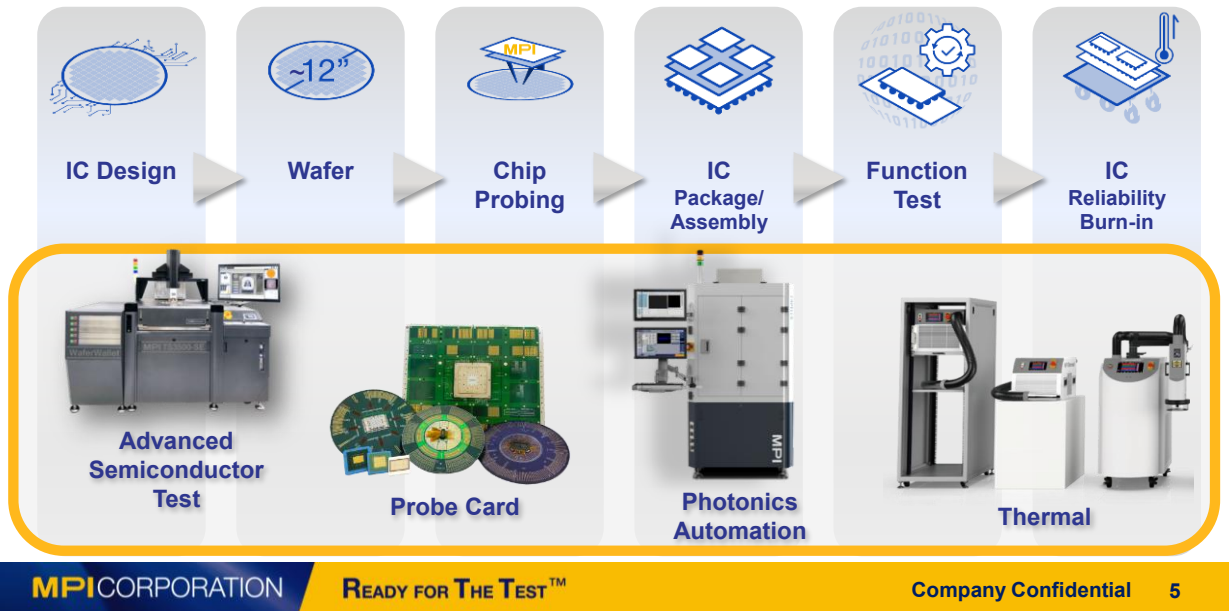


Xinyu Office
TW (2014)



3rd Production Site
TW (2021)

MPI The Powerhouse of Testing Solutions



MPI CORPORATION

READY FOR THE TEST™

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Business Contents

- Probe Card
- Photonics Automation
- Thermal & AST



Financial Statements

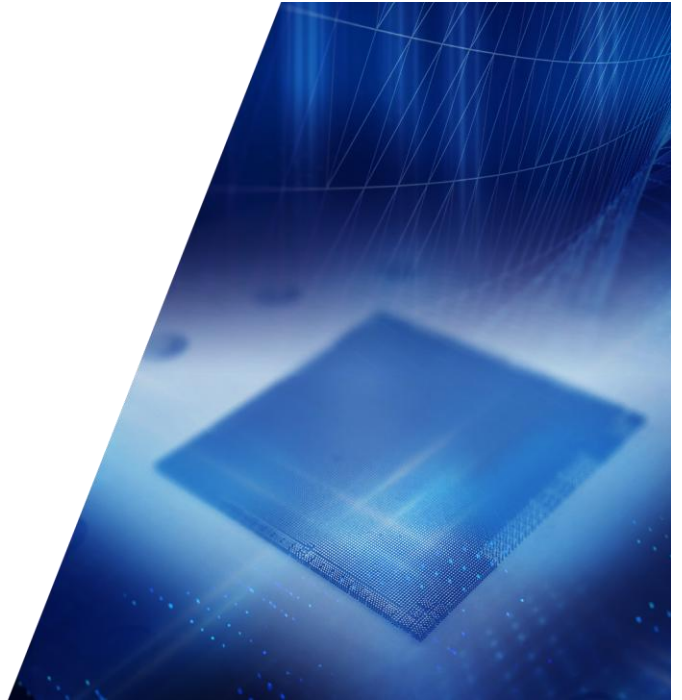
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Probe Card

半導體事業部
(探針卡)



MPIProbe Card

Advanced Wafer Sort Test Solutions

Vertical / MEMS Cantilever



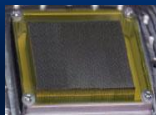
Features



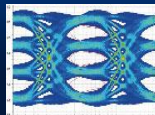
Fine Pitch



MEMS



High Pin Count



High Speed



Substrate



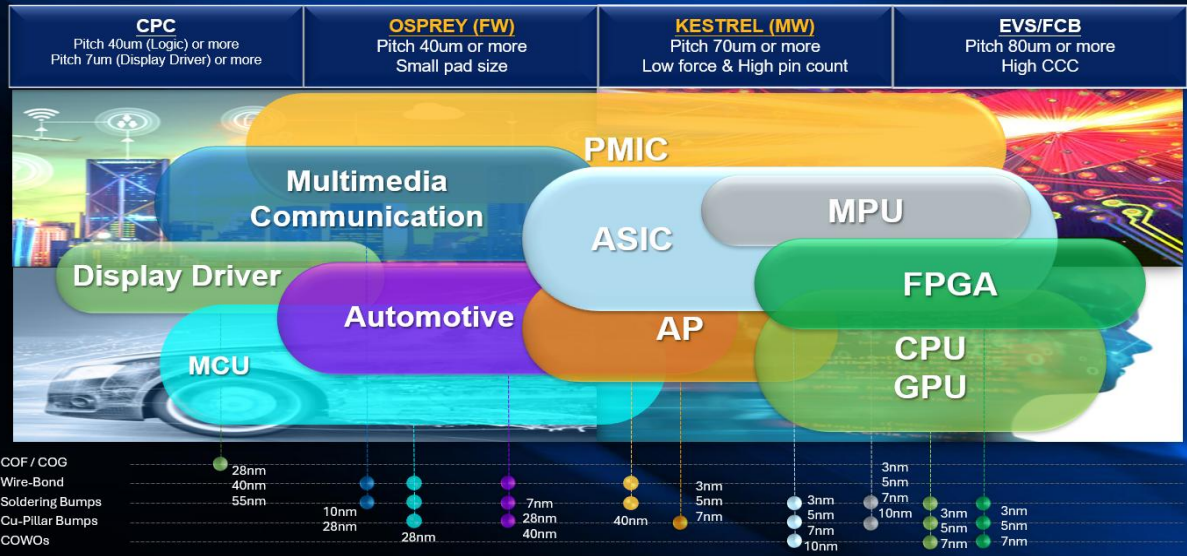
Hand-wired



RF

MPI Probe Card

Full range of products for the applications
sufficient coverage solutions to IC markets

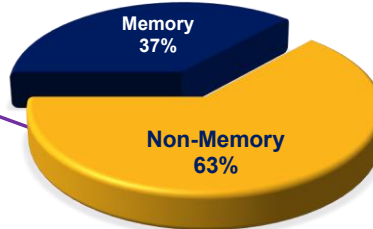


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MPI 全球探針卡市場

Semiconductor Probe Cards

US\$3.4B in 2026/
CAGR 4.9% 2026-31



Cantilever
\$284M , 2.9% CAGR

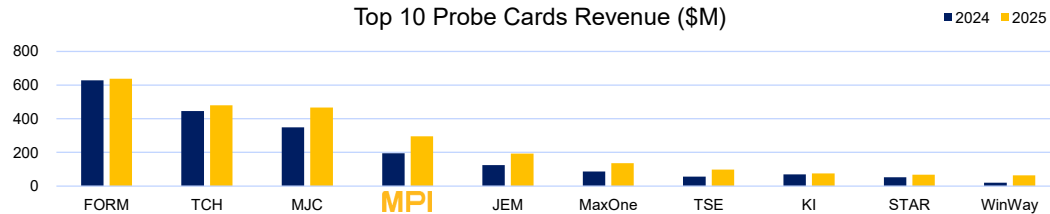
Vertical
\$540M , 3.6% CAGR

MEMS
\$2,426M , 5.6% CAGR

Source: YOLE(2026)

MPI 自製IC探針卡供應商

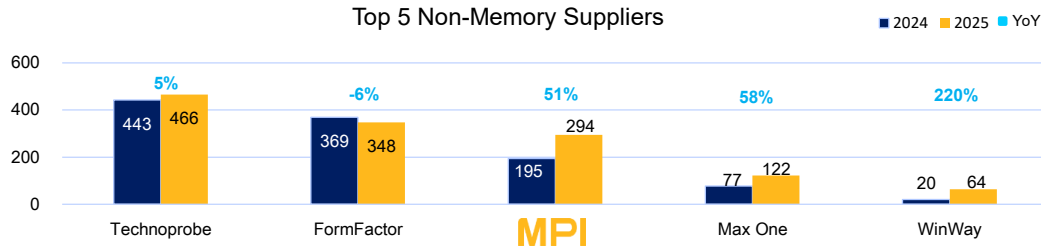
(Rank)		2021	2022	2023	2024	2025
FormFactor	USA	1	1	1	1	1
Technoprobe	Italy	2	2	2	2	2
Micronics Japan	Japan	3	3	3	3	3
MPI Corporation	Taiwan	5	5	4	4	4
Japan Electronic Materials	Japan	4	4	5	5	5



Source: YOLE(2026)

MPI 前五大非記憶體探針卡供應商

(Rank)		2020	2021	2022	2023	2024	2025
Technoprobe	Italy	2	1	1	1	1	1
FormFactor	USA	1	2	2	2	2	2
MPI Corporation	Taiwan	3	3	3	3	3	3
Max One	CH		16	13	6	4	4
Winway	Taiwan		19	10	18	15	5



Source: YOLE(2026)

MPI Probe Card: 提供全方位解決方案

- **Comprehensive Product Range for Circuit Testing** 全方位的產品布局

MPI provides omnidirectional products to global customers, including fine pitch CPC, high speed VPC and low force MEMS solutions.

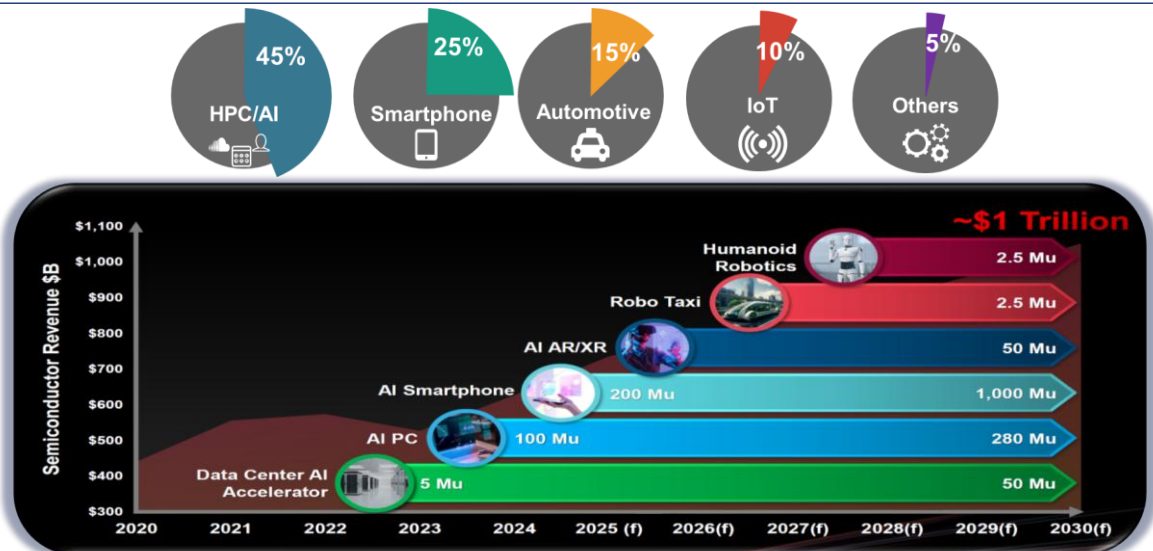
- **Solid Global Clientele** 堅實的國際合作夥伴

MPI works closely with worldwide market leaders, especially for the AI, HPC application related.

- **Complete Probe Card Solution** 完整的探針卡整合方案

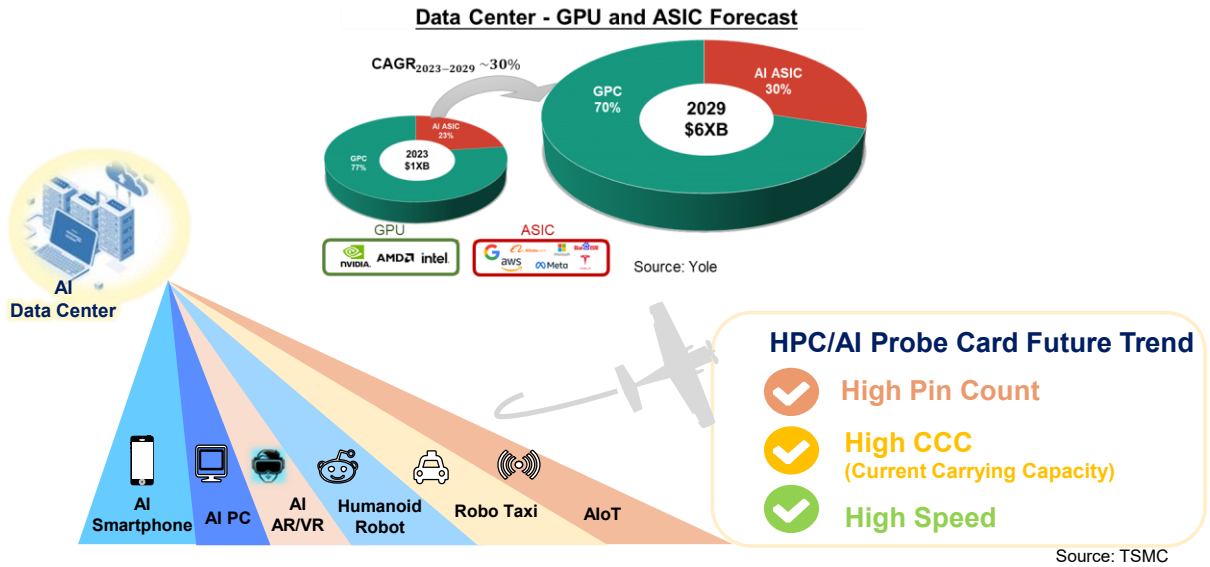
Provide probe head, substrate(MLO/MLC/MLOC) and PCB one-stop service.

MPI 2030 半導體市場~\$1Trillion



Source: TSMC

MPI HPC/AI 探針卡挑戰



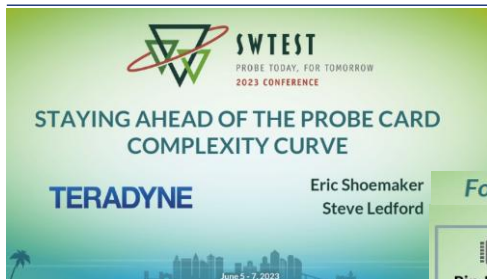
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MPI Interface Technical Complexity Check in



Following the "2 x 4 Scaling" trend demonstrated over last two decades

		Today	2030
Pin Density	Increasing DUT sites and pin count drive up the pin area density Challenge: Routing the I/O and power to the DUT combined with an increasing mechanical load	70 um pad pitch 16,000 pins per cm ² 150+ Kg (total contact)	30 um pad pitch 64,000+ pins per cm ² 300+ Kg (total contact)
I/O	Connections to high performance I/O: high speed digital, wireless, and high voltage Challenge: Signal integrity when combined with very tight pin and DUT spacing and high DUT count	112 Gbps (dig) 54 GHz (5G) 2 kV (automotive)	400+ Gbps (dig) 110+ GHz (6G) 8 kV (automotive)
Power	Large number of high current (>25A) device supplies require excellent precision Challenge: Supply voltage reduction (<700mV) combined with increasing number of power rails	700 mV (main power) 750 A (single rail) 500 μOhm (impedance)	<500 mV (main power) 2000 A (single rail) 100 μOhm (impedance)
Thermal	Removal of the DUT thermal energy due to self heating and support increased operating temp ranges Challenge: Increasing transistor count combined with tight DUT spacing rapidly increases thermal density	0.5 KW (self heating) 0C to +125C	1.0 KW (self heating) -40C to +160C

Source: Teradyne

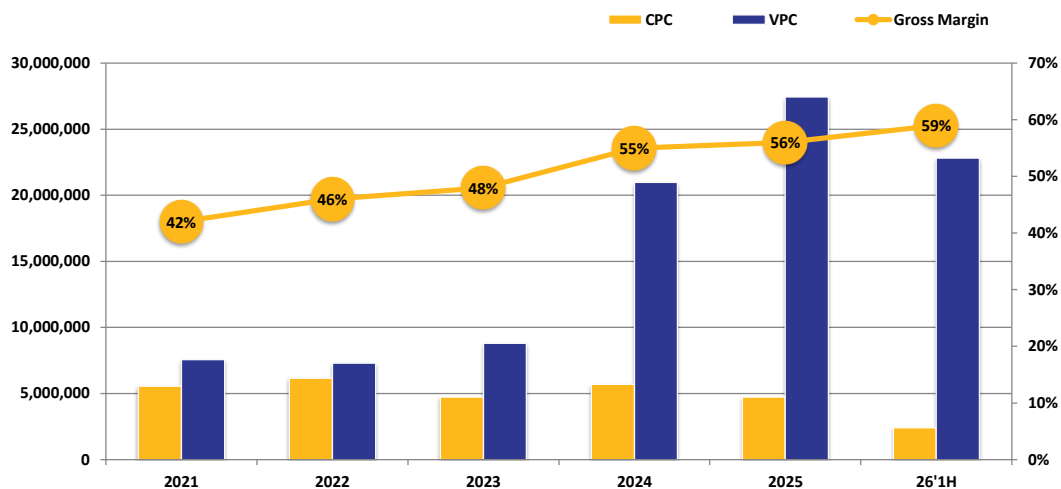
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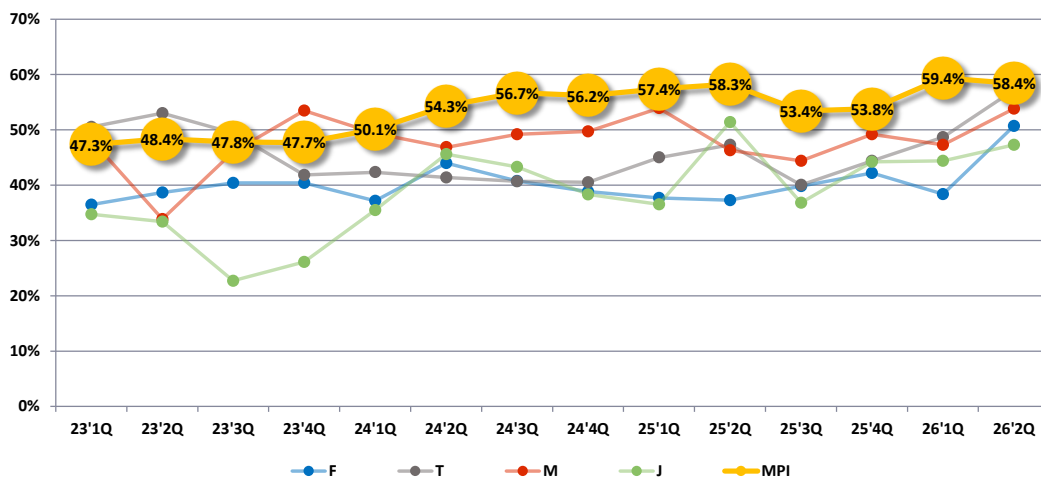
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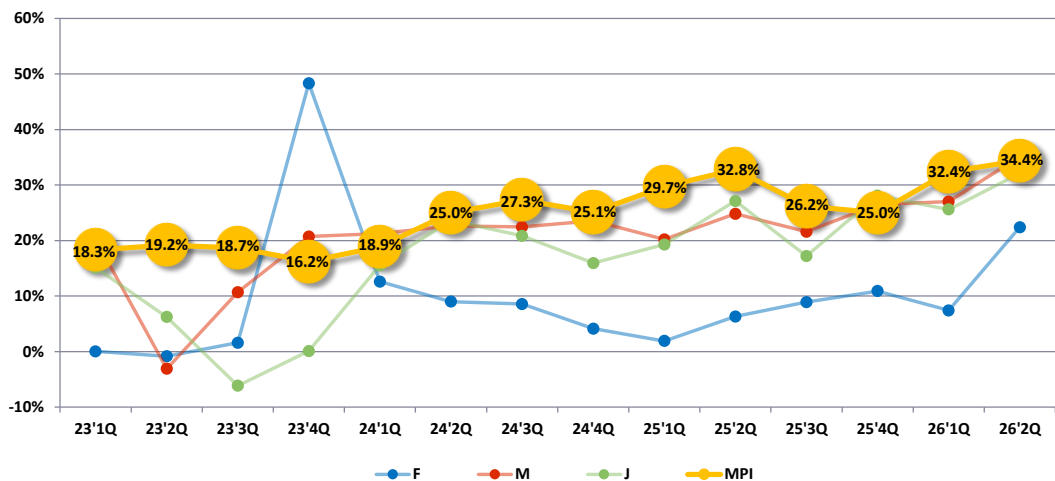
MPI CPC & VPC成長趨勢



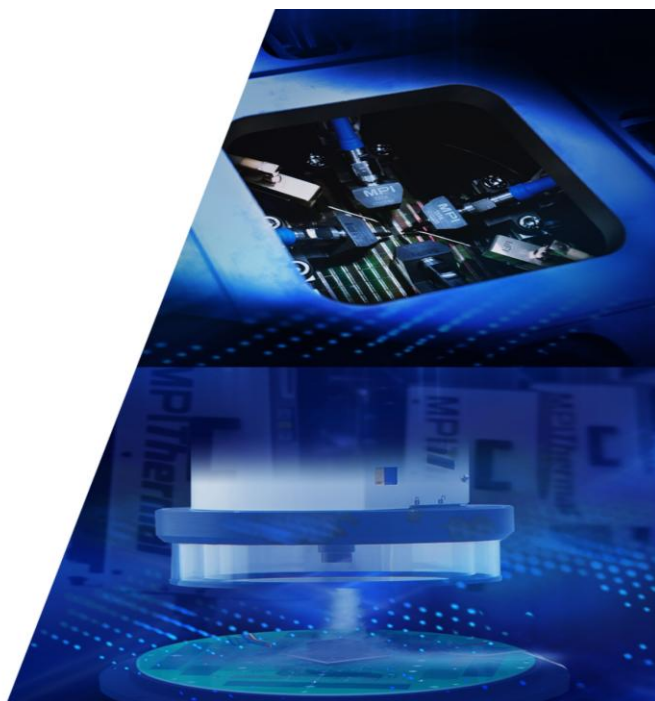
MPI 全球同業毛利率



MPI 全球同業營利率



Thermal/AST



MPI Thermal

Hot and Cold Air Flow
Environmental Temperature Test

-100°C  +300°C
ThermalAir Series
Temperature Testing Systems



Applications & Industry Segments



Semiconductor



Automotive



Aerospace



Telecommunications



Fiber Optic



Electronics



Sensors



Advanced Technology

MPI CORPORATION

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MPI Thermal: 客戶導向

● Innovative Temperature System 創新的溫度測試系統

Ongoing R&D investments in platforms and improvements leads MPI to meet customer demands. Thermal systems have a number of patents to provide efficient energy saving products that helps clients to fulfill ESG responsibility.

● Top Skillful RD Team 頂尖優秀專業的研發團隊

MPI's thermal solutions are developed by industry veterans with over 100 years of combined experience.

● Deep Cooperation with Leading Customers for Engineering and Production demand

與世界領導級大廠深度合作, 提供工程及量產需求

Product application expands to automotive , 5G/RF communication , fiber optic , and sensing fields.

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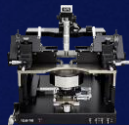
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MPI Advanced Semiconductor Test

Engineering Probe Systems
and
RF Probe Products



50 – 300 mm

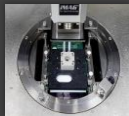


26 – 110 GHz

Applications & Industry Segments



Device Characterization



High Power



RF & mmW



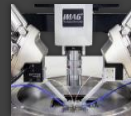
Design Validation



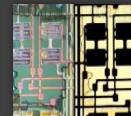
Failure Analysis



Wafer Level Reliability



Silicon Photonics



Laser Cutter

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MPI AST: 獨特的市場領導者

● Unique Global Position 全球獨特的市場地位

Combining Analytical probing solution and RF measurement core technology, MPI is top solution provider for full range hi-frequency response measurement.

● VOC Design 客戶導向設計

Design based on Voice of the customer to full-fill customers' needs.

● Complete Solution 提供完整的解決方案

Various series of products to cover wide range applications include Device Modeling, RF & mmW, WLR, High-Power, Failure Analysis, Extreme temperature test ...etc.

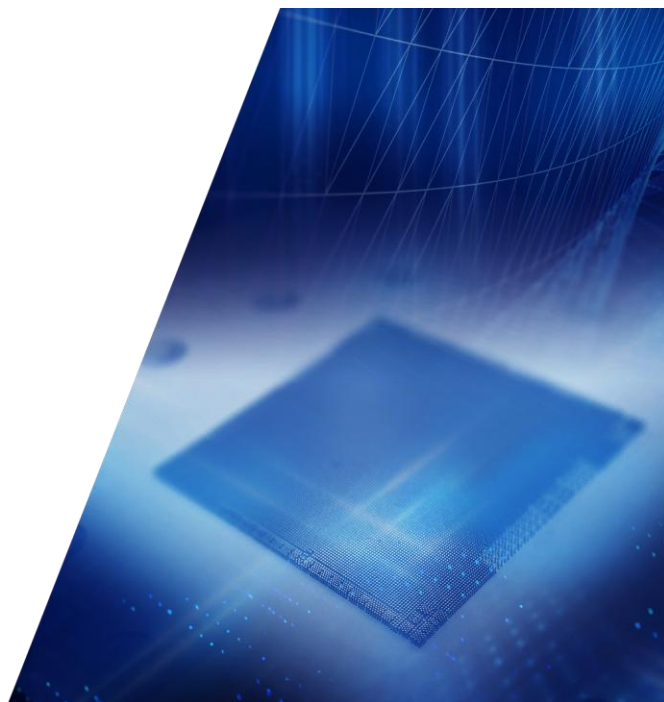
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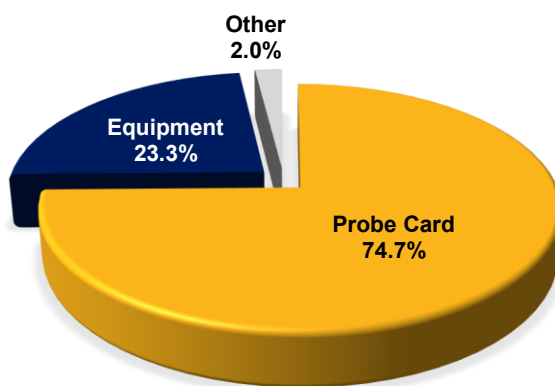
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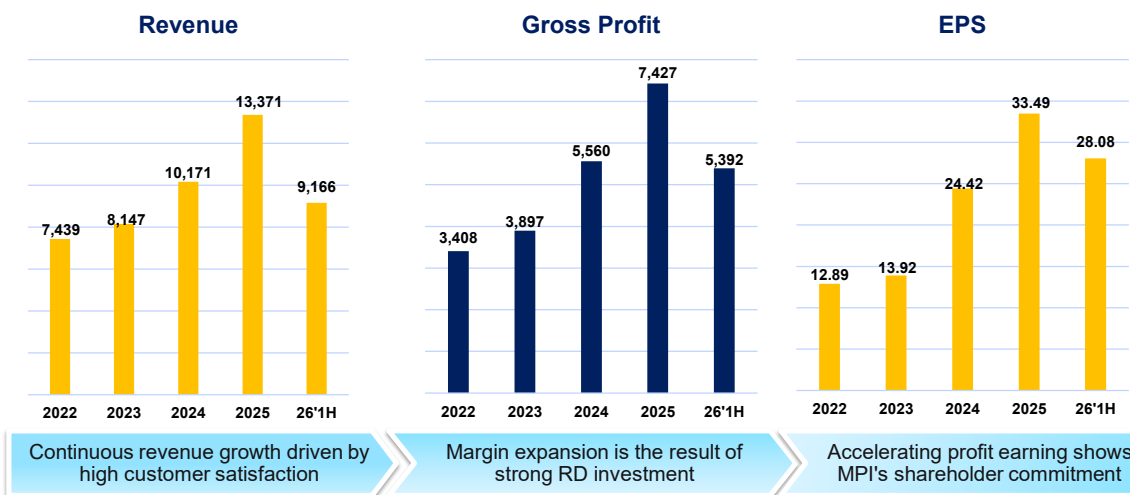
財務報表



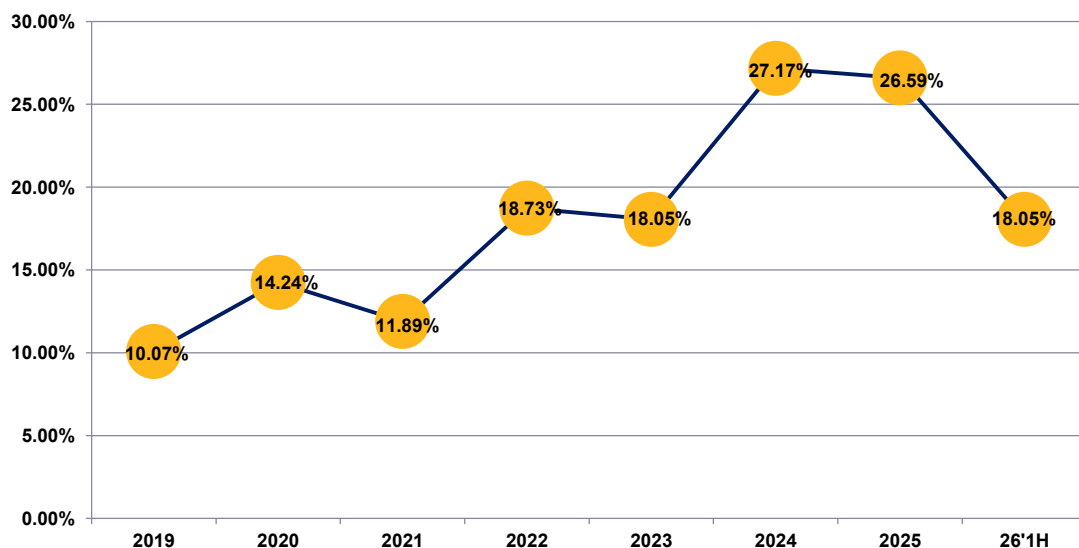
MPI 2025 營收分布



MPI 營業表現



MPI 股東權益報酬率



MPI 資產負債表

NT\$M	2026 1H		2025 1H	
Cash and Cash Equivalents	9,879	28%	5,637	28%
Fixed Assets	15,661	44%	8,619	43%
Total Assets	35,415	100%	20,123	100%
LT Debt	2,159	6%	1,152	6%
Shareholders' Equity	15,904	45%	9,392	47%
EBITDA	3,431	38%	1,643	27%

*EBITDA=operating income + depreciation & amortization expenses

MPI 綜合損益表

NT\$K	2026 2Q		2025 2Q		YoY	2026 1Q		QoQ
Net Sales	5,233,387	100%	3,292,785	100%	58.9%	3,933,067	100%	33.1%
Cost of Goods Sold	2,178,536	42%	1,373,511	42%	58.6%	1,773,148	46%	22.9%
Gross Profit	3,054,851	58%	1,919,274	58%	59.2%	2,338,079	59%	30.7%
Operating Expense	1,253,000	24%	840,212	25%	49.1%	1,065,069	27%	17.6%
Operating Income	1,801,851	34%	1,079,062	33%	67.0%	1,273,010	32%	41.5%
Investment Income & Others	104,226		-322,830		132.3%	252,184		-58.7%
Net Income (after tax)	1,523,821	29%	627,916	19%	142.7%	1,227,478	31%	24.1%
EPS (after tax)	15.55		6.67			12.53		

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Thank You.

<http://www.mpi-corporation.com>